

## THE UNITED STATES PATENT AND TRADEMARK OFFICE

**REVOCATION AND NEW POWER OF ATTORNEY AND  
CHANGE OF CORRESPONDENCE ADDRESS**

I, *Dr. Graham Fisher, Director of Intellectual Property of MEMC Electronic Materials, Inc.*, the Assignee of the entire right, title, and interest in the *U.S. Patent Application(s) and/or Patent(s) identified on the attached Schedule A*, hereby revoke all previous powers of attorney or authorizations of agent given and do hereby appoint the attorneys or agents associated with the following Customer Number, with full power of substitution and revocation, to prosecute and transact all business in the Patent and Trademark Office connected therewith for the *U.S. Patent Application(s) and/or Patent(s) listed in the attached Schedule A*:

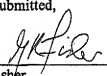
*Customer Number: 76681*

Please direct all correspondence in connection with said *U.S. Patent Application(s) and/or Patent(s)* to:

*Customer Number: 76681*

Respectfully submitted,

Date: 5/13/2008

  
\_\_\_\_\_  
Dr. Graham Fisher  
Director of Intellectual Property  
MEMC Electronic Materials, Inc.

PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

**STATEMENT UNDER 37 CFR 3.73(b)**


***MEMC Electronic Materials, Inc.***, a Delaware Corporation, pursuant to 37 CFR 3.73(b), hereby states that it is the Assignee of the entire right, title, and interest in ***U.S. Patent Application(s) and/or Patent(s) on the attached Schedule A.***

The entire rights, title, and interest in the aforementioned Patent Application(s) and/or Patent(s) were conveyed to ***MEMC Electronic Materials, Inc.*** via Assignment(s) recorded with the United States Patent and Trademark Office at the ***Reel/Frame Numbers on the attached Schedule A.***

The undersigned, ***Dr. Graham Fisher, Director of Intellectual Property***, has full authorization to act on behalf of Assignee ***MEMC Electronic Materials, Inc.***

Respectfully submitted,

Date: 5/13/2008

  
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Dr. Graham Fisher  
Director of Intellectual Property  
MEMC Electronic Materials, Inc.

**APPENDIX A**  
**Owned by MEMC Electronic Materials, Inc.**

ATTORNEY REFERENCE	CONF. NO	PUBLICATION NO. & DATE	SERIAL NO. FILING DATE	PATENT NO. ISSUE DATE	CURRENT OWNER/ ASSIGNEE	REEL AND FRAME NO.	TITLE
MEMC3043.1	3075		08/20/593 3/18/1967	5,834,812 11/10/1998	MEMC Electronic Materials, Inc.	Division of 08/346,895 007,391,039X	EDGE STRIPPED BESOI WAFER
MEMC3053	5338	US-2005-0016443 A1 1/27/2005	10/623,967 7/12/2003	6,960,254 11/1/2005	MEMC Electronic Materials, Inc.	01431203996	METHOD TO MONITOR AND CONTROL THE CRYSTAL COOLING OR QUENCHING RATE BY MEASURING CRYSTAL SURFACE TEMPERATURE
28744-153 (MEMC3054.1)	5594	US-2007-0074653 A1 4/12/2007	11/024,143 9/30/2005		MEMC Electronic Materials, Inc.	0168760126	APPARATUS FOR PREPARATION OF SILICON CRYSTALS WITH REDUCED METAL CONTENT
MEMC3057	3909	US-2004-0235402 A1 11/25/2004	10/442,900 5/22/2006	7,006,308 3/7/2006	MEMC Electronic Materials, Inc.	0137780746	WAFER CARRIER
MEMC3067.1	6872	US-2008-0011688 A1 1/19/2008	11/152,382 5/14/2005	7,323,421 1/29/2006	MEMC Electronic Materials, Inc.	0165960425	SILICON WAFER ETCHING PROCESS AND COMPOSITION
28744-217 (MEMC3070.1)	9113	US-2006-0136601 A1 6/28/2006	11/104,544 4/13/2005		MEMC Electronic Materials, Inc.	0192000665	INTERNALLY GETTERED HETEROEPIAXIAL SEMICONDUCTOR WAFERS AND METHODS OF MANUFACTURING SUCH WAFERS
MEMC3073	9463	US-2005-0250293 A1 11/10/2005	01940,854 5/7/2004	7,094,048 8/12/2006	MEMC Electronic Materials, Inc.	0149710329	PROCESS FOR METALLIC CONTAMINATION REDUCTION IN SILICON WAFERS
28744-108 (MEMC3077.1)	1776	US-2005-0016833 A1 1/28/2005	10/636,146 3/23/2004		MEMC Electronic Materials, Inc.	0163370767	PARTIALLY DEHYDRIFIED CRUCIBLE
MEMC3077.1	7618	US-2005-0217927 A1 12/22/2005	10/930,654 8/31/2004	7,281,222 11/8/2007	MEMC Electronic Materials, Inc.	0143900001	SYSTEMS AND METHODS FOR MEASURING AND REDUCING DUST IN GRANULAR MATERIAL
28744-157 (MEMC3084.1)	4589	US-2005-027878 A1 12/22/2005	11/155,385 9/17/2005		MEMC Electronic Materials, Inc.	0187060613	MELTER ASSEMBLY AND METHOD FOR CHARGING A CRYSTAL FORMING APPARATUS WITH MOLTEN SOURCE MATERIAL
MEMC3084.4	3763	US-2005-027876 A1 12/22/2005	11/155,105 9/17/2005	7,344,584 3/16/2006	MEMC Electronic Materials, Inc.	0186640061	MELTER ASSEMBLY AND METHOD FOR CHARGING A CRYSTAL FORMING APPARATUS WITH MOLTEN SOURCE MATERIAL
28744-150 (MEMC3084.5)	3746	US-2005-0219275 A1 12/22/2005	11/155,104 9/17/2005		MEMC Electronic Materials, Inc.	0186330100	MELTER ASSEMBLY AND METHOD FOR CHARGING A CRYSTAL FORMING APPARATUS WITH MOLTEN SOURCE MATERIAL
MEMC3084	8527	US-2008-0144302 A1 7/19/2008	11/027,360 12/30/2004	7,291,221 11/6/2007	MEMC Electronic Materials, Inc.	0161410710	ELECTROMAGNETIC PUMPING OF LIQUID SILICON IN A CRYSTALLINE GROWING PROCESS
28744-104 (MEMC3091.1)	8286	US-2007-0105279 A1 8/10/2007	11/270,790 11/6/2005		MEMC Electronic Materials, Inc.	0177630557	ARSENIC AND PHOSPHORUS DOPED SILICON WAFER SUBSTRATES HAVING INTRINSIC GETTERING
28744-102 (MEMC3092.1)	8970	US-2008-0263867 A1 11/22/2008	11/426,638 5/19/2006		MEMC Electronic Materials, Inc.	0179490383	HIGH RESISTIVITY SILICON STRUCTURE AND A PROCESS FOR THE PREPARATION THEREOF
28744-103 (MEMC3094)	8834	US-2007-0024989 A1 2/2/2006	10/900,938 7/27/2004		MEMC Electronic Materials, Inc.	0162940081	METHOD FOR PURIFYING SILICON CARBIDE COATED STRUCTURES
MEMC3101	1084	US-2008-0144321 A1 7/19/2008	11/026,780 12/30/2004	7,223,304 5/29/2007	MEMC Electronic Materials, Inc.	0181670533	CONTROLLING MELT-SOLID INTERFACE SHAPE OF A GROWING SILICON CRYSTAL USING A VARIABLE MAGNETIC FIELD
MEMC3104	4384		11/041,583 1/24/2006	7,003,169 4/25/2006	MEMC Electronic Materials, Inc.	0159910658	SEMICONDUCTOR WAFER BOAT FOR A VERTICAL FURNACE